

## Automotive-grade N-channel 24 V, 0.95 mΩ typ., 180 A STripFET™ III Power MOSFET in a H<sup>2</sup>PAK-6 package

Datasheet – production data

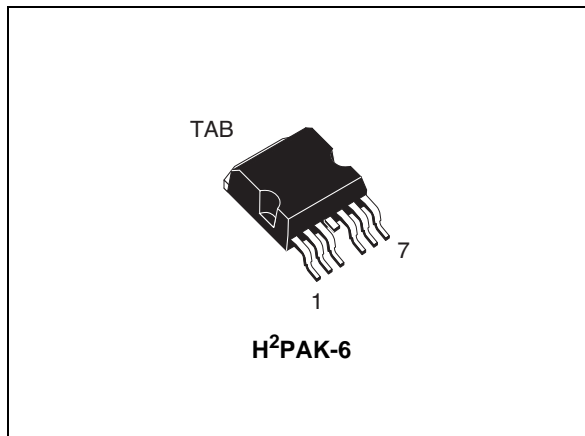
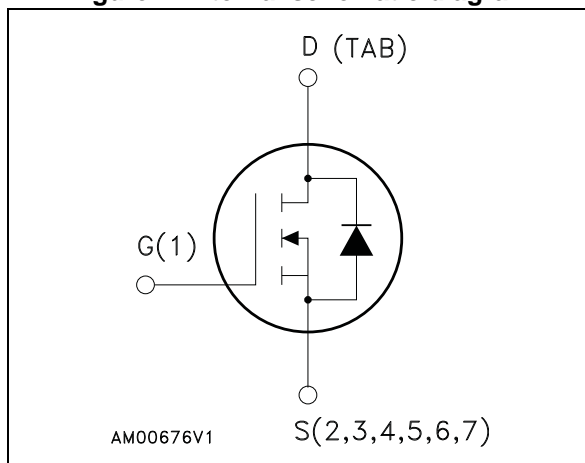


Figure 1. Internal schematic diagram



### Features

Order code	V <sub>DSS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub> <sup>(1)</sup>
STH300NH02L-6	24 V	< 1.2 mΩ	180 A

1. Current limited by package.

- Designed for automotive applications and AEC-Q101 qualified
- Conduction losses reduced
- Low profile, very low parasitic inductance, high current package

### Applications

- Switching applications

### Description

This device is an N-channel enhancement mode Power MOSFET produced using STMicroelectronics' STripFET™ III technology, which is specifically designed to minimize on-resistance and gate charge to provide superior switching performance.

Table 1. Device summary

Order code	Marking	Package	Packaging
STH300NH02L-6	300NH02L	H <sup>2</sup> PAK-6	Tape and reel

# Contents

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-source voltage	24	V
$V_{GS}$	Gate-source voltage	$\pm 20$	V
$I_D^{(1)}$	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	180	A
$I_D^{(1)}$	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	180	A
$I_{DM}^{(2)}$	Drain current (pulsed)	720	A
$P_{TOT}^{(3)}$	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	300	W
	Derating factor	2	W/°C
$E_{AS}^{(4)}$	Single pulse avalanche energy	1.6	J
$T_{stg}$	Storage temperature	-55 to 175	°C
$T_j$	Operating junction temperature		

1. Current limited by package
2. Pulse width limited by safe operating area
3. This value is rated according to  $R_{thj-c}$
4. Starting  $T_j = 25\text{ }^\circ\text{C}$ ,  $I_D = 60\text{ A}$ ,  $V_{DD} = 20\text{ V}$

**Table 3. Thermal data**

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	0.5	°C/W
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb max	35	°C/W

1. When mounted on 1 inch<sup>2</sup> FR-4 2 oz Cu.

## 2 Electrical characteristics

(T<sub>case</sub> = 25 °C unless otherwise specified)

**Table 4. On /off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage (V <sub>GS</sub> = 0)	I <sub>D</sub> = 250 μA	24			V
I <sub>DSS</sub>	Zero gate voltage drain current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = 24 V, V <sub>DS</sub> = 24 V, T <sub>C</sub> = 125 °C			1 10	μA μA
I <sub>GSS</sub>	Gate body leakage current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 20 V			± 100	nA
V <sub>GS(th)</sub>	Gate threshold voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA	1			V
R <sub>DS(on)</sub>	Static drain-source on-resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 80 A V <sub>GS</sub> = 5 V, I <sub>D</sub> = 40 A		0.95 1.15	1.2 1.5	mΩ

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C <sub>iss</sub>	Input capacitance	V <sub>DS</sub> = 15 V, f = 1 MHz, V <sub>GS</sub> = 0	-	7050	-	pF
C <sub>oss</sub>	Output capacitance		-	3250	-	pF
C <sub>rss</sub>	Reverse transfer capacitance		-	307	-	pF
Q <sub>g</sub>	Total gate charge	V <sub>DD</sub> = 20 V, I <sub>D</sub> = 120 A, V <sub>GS</sub> = 10 V (see Figure 14)	-	109	-	nC
Q <sub>gs</sub>	Gate-source charge		-	30	-	nC
Q <sub>gd</sub>	Gate-drain charge		-	26	-	nC

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time	V <sub>DD</sub> = 20 V, I <sub>D</sub> = 80 A R <sub>G</sub> = 4.7 Ω, V <sub>GS</sub> = 10 V, (see Figure 13)	-	18	-	ns
t <sub>r</sub>	Rise time		-	275	-	ns
t <sub>d(off)</sub>	Turn-off delay time	V <sub>DD</sub> = 20 V, I <sub>D</sub> = 80 A R <sub>G</sub> = 4.7 Ω, V <sub>GS</sub> = 10 V, (see Figure 13)	-	138	-	ns
t <sub>f</sub>	Fall time		-	94.4	-	ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}^{(1)}$	Source-drain current		-		180	A
$I_{SD}^{(2)}$	Source-drain current (pulsed)		-		720	A
$V_{SD}^{(3)}$	Forward on voltage	$I_{SD} = 180 \text{ A}, V_{GS} = 0$	-		1.3	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 120 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$	-	65		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 20 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$	-	90		nC
$I_{RRM}$	Reverse recovery current	(see Figure 15)	-	2.8		A

1. Current limited by package
2. Pulse width limited by safe operating area
3. Pulsed: Pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area

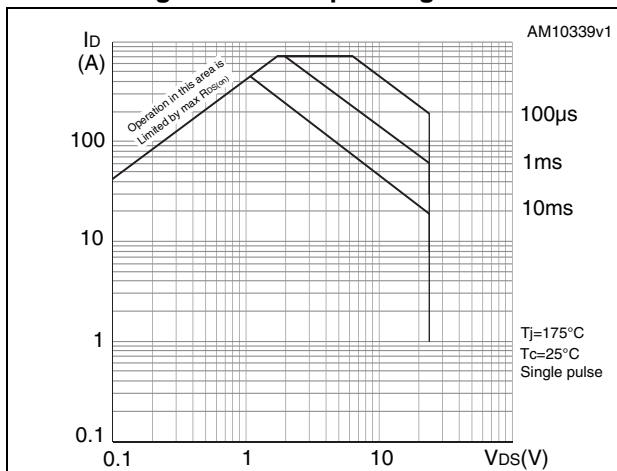


Figure 3. Thermal impedance

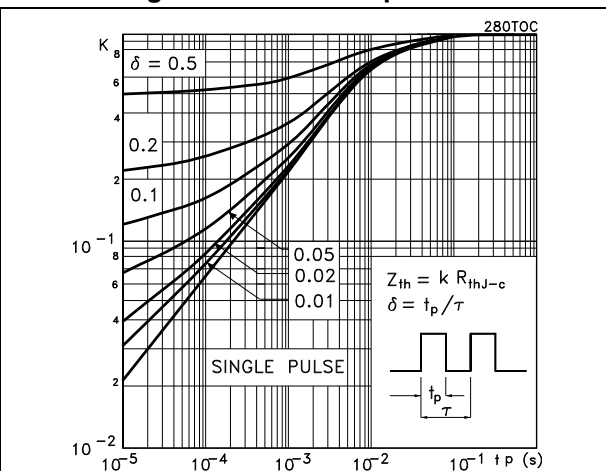


Figure 4. Output characteristics

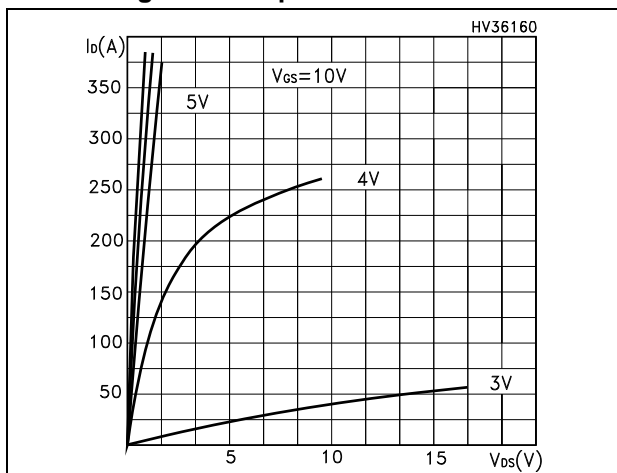


Figure 5. Transfer characteristics

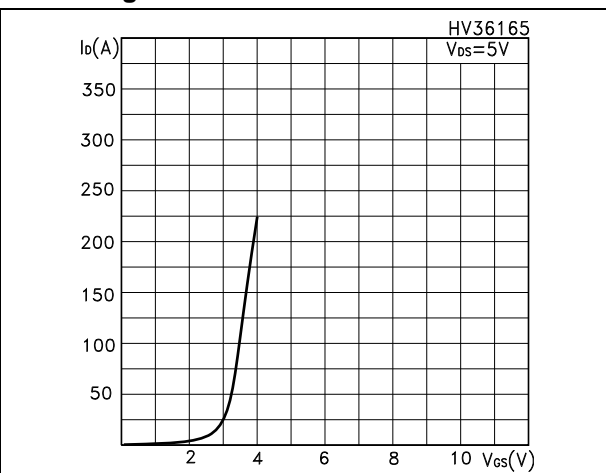


Figure 6. Normalized B<sub>VDS</sub> vs temperature

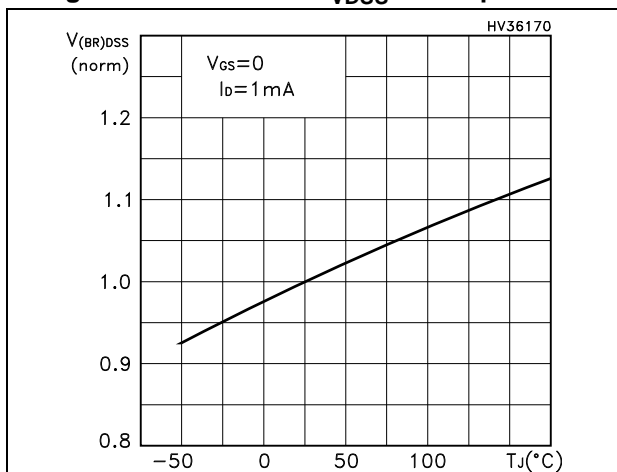


Figure 7. Static drain-source on-resistance

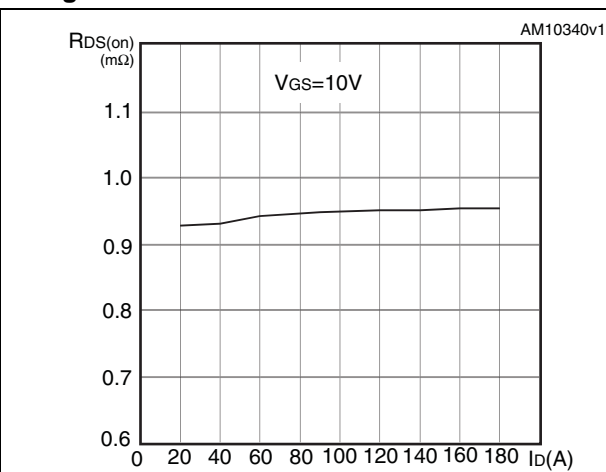


Figure 8. Gate charge vs gate-source voltage

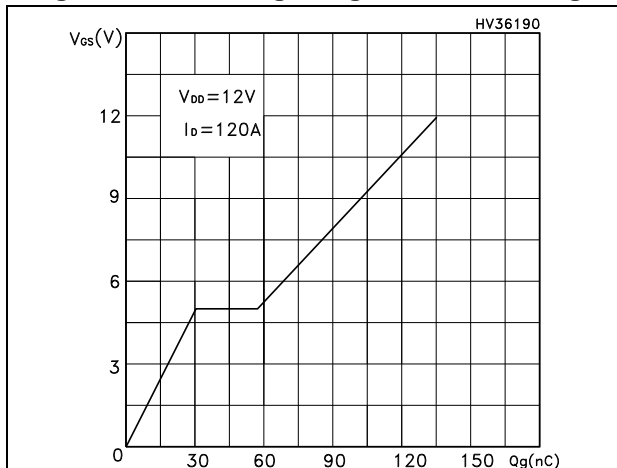


Figure 9. Capacitance variations

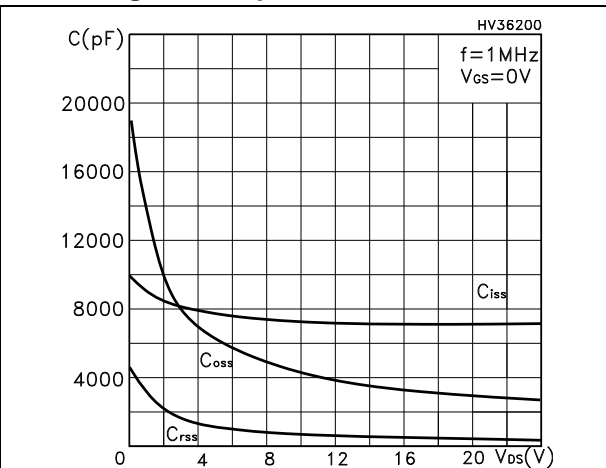


Figure 10. Normalized gate threshold voltage vs temperature

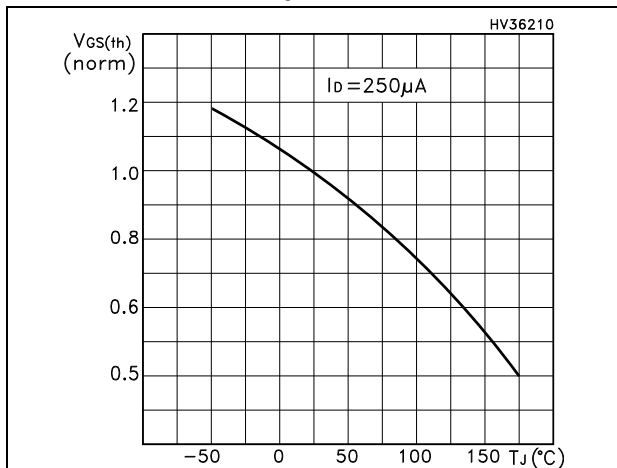


Figure 11. Normalized on resistance vs temperature

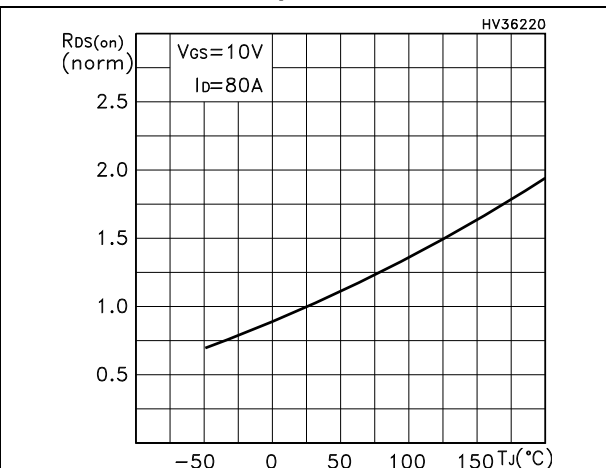
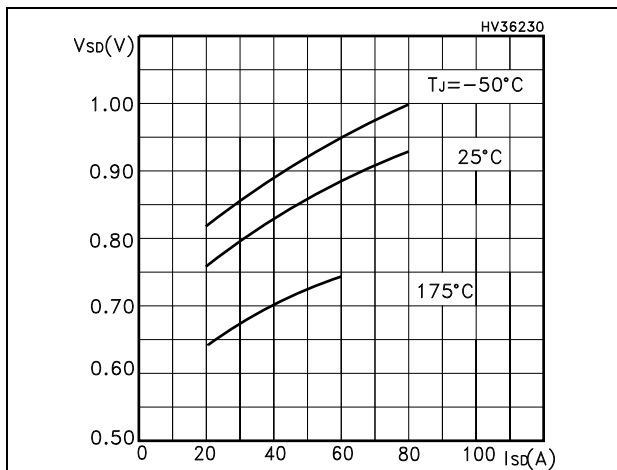


Figure 12. Source-drain diode forward characteristics



### 3 Test circuits

Figure 13. Switching times test circuit for resistive load



Figure 14. Gate charge test circuit



Figure 15. Test circuit for inductive load switching and diode recovery times



Figure 16. Unclamped inductive load test circuit



Figure 17. Unclamped inductive waveform



Figure 18. Switching time waveform





## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

**Table 8. H<sup>2</sup>PAK-6 mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.30		4.80
A1	0.03		0.20
C	1.17		1.37
e	2.34		2.74
e1	4.88		5.28
e2	7.42		7.82
E	0.45		0.60
F	0.50		0.70
H	10.00		10.40
H1	7.40		7.80
L	14.75		15.25
L1	1.27		1.40
L2	4.35		4.95
L3	6.85		7.25
L4	1.5		1.75
M	1.90		2.50
R	0.20		0.60
V	0°		8°

Figure 19. H<sup>2</sup>PAK-6 drawing

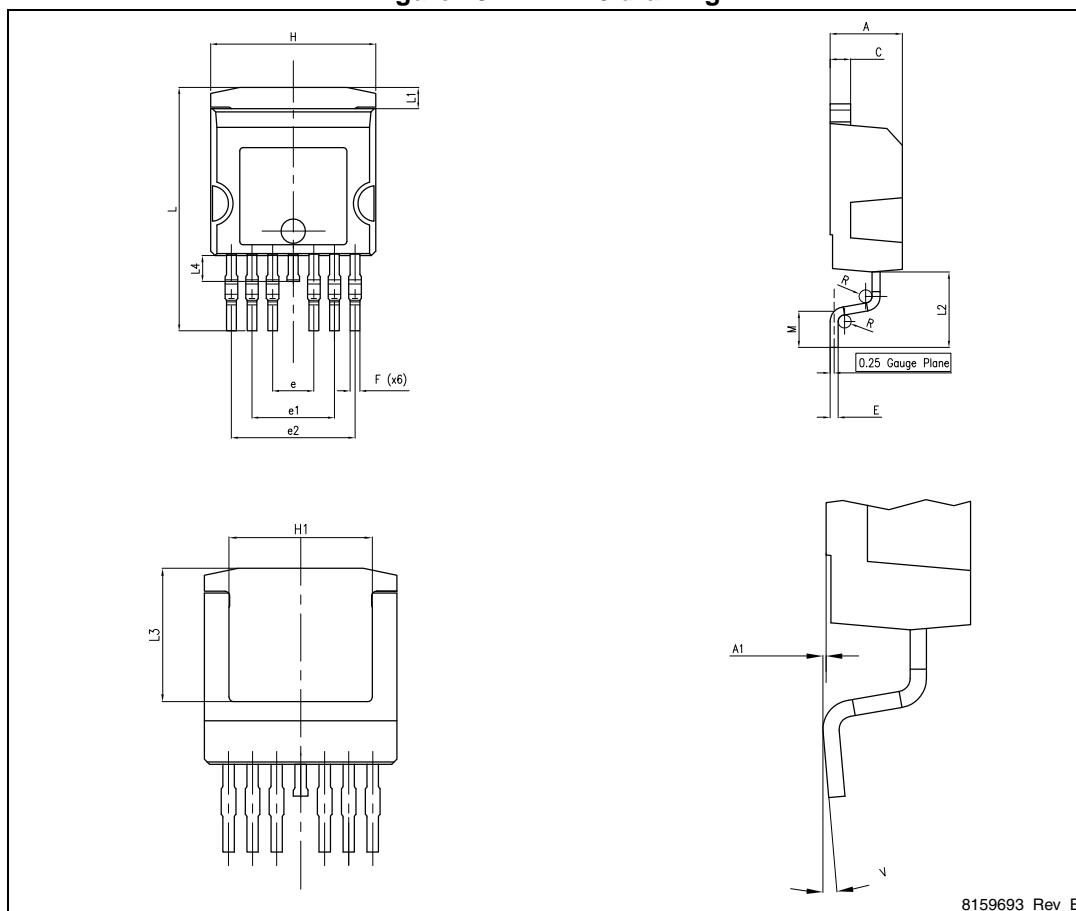
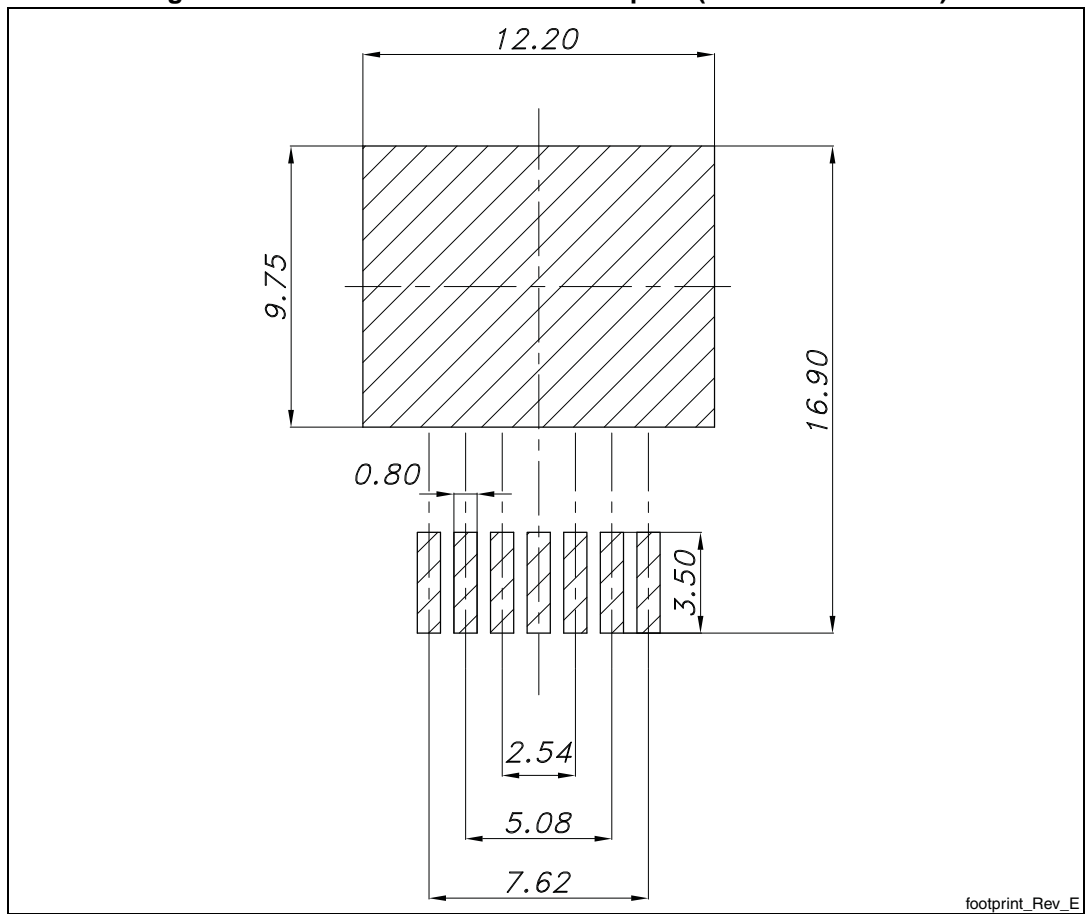


Figure 20. H<sup>2</sup>PAK-6 recommended footprint (dimensions in mm)



## 5 Packaging mechanical data

Table 9. Tape and reel mechanical data

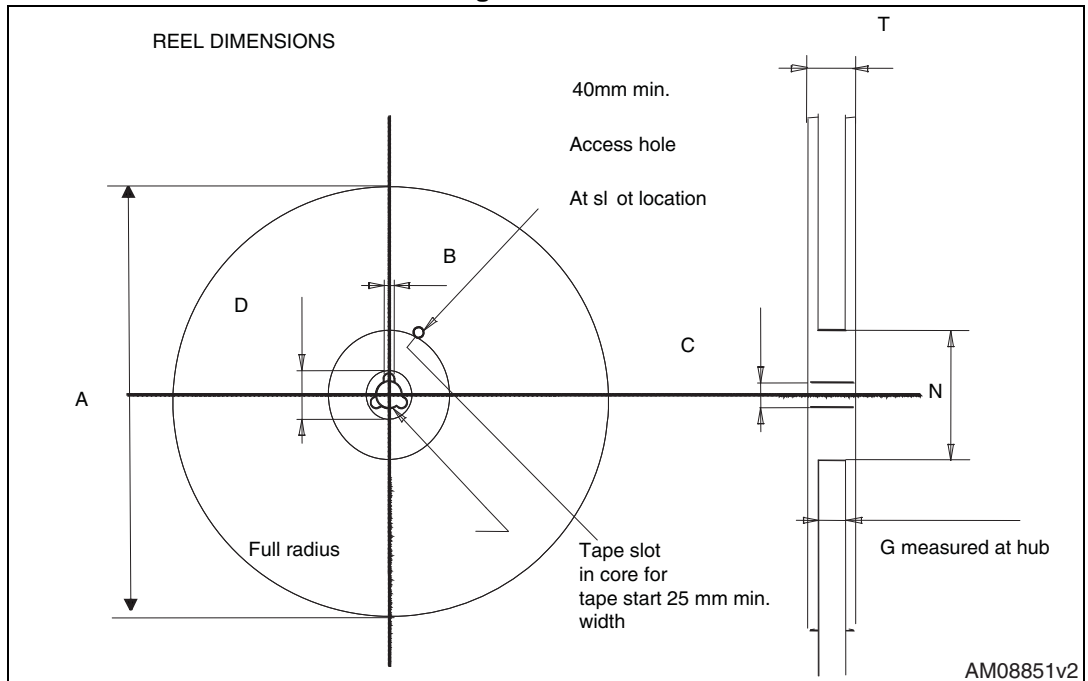
Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base qty		1000
P2	1.9	2.1	Bulk qty		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

Figure 21. Tape



AM08852v2

Figure 22. Reel



AM08851v2

## 6 Revision history

Table 10. Document revision history

Date	Revision	Changes
12-Jul-2011	1	initial release
24-Oct-2011	2	Updated test conditions in <a href="#">Section Table 5.: Dynamic</a> and <a href="#">Section Table 7.: Source drain diode</a> .
15-May-2013	3	– Updated: title, <a href="#">Applications</a> and <a href="#">Description</a> in cover page – Minor text changes
22-Jul-2013	4	– Updated title in cover page.

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